



Material Content Data Sheet



Sales Product Name	SGB15N60			Issued		29. August 2013		
MA#	MA000598582							
Package	PG-TO263-3-2			Weight*		1462.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.392	0.23	0.23	2320	2320
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.22	58.30	582328	583086
wire	non noble metal	aluminium	7429-90-5	2.717	0.19	0.19	1858	1858
encapsulation	organic material	carbon black	1333-86-4	8.860	0.61		6058	
	plastics	epoxy resin	-	97.457	6.66		66634	
	inorganic material	silicondioxide	60676-86-0	484.330	33.12	40.39	331151	403843
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6603	6603
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.078	0.01		53	
	non noble metal	tin	7440-31-5	0.062	0.00		43	
	non noble metal	lead	7439-92-1	2.980	0.20	0.21	2038	2134
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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